



Flip Chip Bumping Factory Qualification at SPIL for Defense-grade 7 Series XQ FPGA Products

XCN16003 (v1.0) June 27, 2016

Product Change Notice - For Information Only

Overview

The purpose of this notification is to communicate that Xilinx has qualified SPIL Bumping for 7 Series FPGAs Defense-grade “XQ” flip chip products.

Description

This notification is to inform customers that 7- Series FPGAs Defense-grade “XQ” flip chip product bumping will be performed at Siliconware Precision Industry Ltd. (SPIL). SPIL has been a Xilinx qualified flip chip bumping and assembly supplier for all XQ and flip chip products, which include Virtex®-II Pro, Virtex-4, Virtex-5 and Virtex-6. All bill of materials, dimensions and major process steps remain unchanged. There is no change to the form, fit, or function.

Products Affected

This change affects all 7 Series FPGAs “XQ” products.

Table 1: 7 Series FPGAs XQ Products Family Affected

Part Number	Part Number	Part Number
XQ7A200T-1RB484I	XQ7K410T-L2RF900E	XQ7VX690T-2RF1761I
XQ7A200T-1RB484M	XQ7K410T-L2RF900I	XQ7VX690T-2RF1930I
XQ7A200T-1RB676I	XQ7V585T-1RF1157I	XQ7VX980T-1RF1930I
XQ7A200T-1RB676M	XQ7V585T-1RF1157M	XQ7VX980T-L2RF1930E
XQ7A200T-1RS484I	XQ7V585T-1RF1761I	XQ7Z030-1RB484I
XQ7A200T-1RS484M	XQ7V585T-1RF1761M	XQ7Z030-1RB484Q
XQ7A200T-2RB484I	XQ7V585T-2RF1157I	XQ7Z030-1RF676I
XQ7A200T-2RB676I	XQ7V585T-2RF1761I	XQ7Z030-1RF676Q
XQ7A200T-2RS484I	XQ7V585T-L2RF1157E	XQ7Z030-2RB484I
XQ7A200T-L1RB484I	XQ7V585T-L2RF1761E	XQ7Z030-2RF676I
XQ7A200T-L1RB676I	XQ7VX330T-1RF1157I	XQ7Z030-L2RB484I
XQ7A200T-L1RS484I	XQ7VX330T-1RF1157M	XQ7Z030-L2RF676I
XQ7K325T-1RF676I	XQ7VX330T-1RF1761I	XQ7Z045-1RF676I
XQ7K325T-1RF676M	XQ7VX330T-1RF1761M	XQ7Z045-1RF676Q
XQ7K325T-1RF900I	XQ7VX330T-2RF1157I	XQ7Z045-1RF900I
XQ7K325T-1RF900M	XQ7VX330T-2RF1761I	XQ7K325T-2RF676I

Table 1 (continued): 7 Series FPGAs XQ Products Family Affected

Part Number	Part Number	Part Number
XQ7K325T-2RF900I	XQ7VX485T-1RF1761I	XQ7Z045-2RF676I
XQ7K325T-L1RF676M	XQ7VX485T-1RF1761M	XQ7Z045-2RF900I
XQ7K325T-L2RF676E	XQ7VX485T-1RF1930I	XQ7Z045-L1RF676Q
XQ7K325T-L2RF676I	XQ7VX485T-1RF1930M	XQ7Z045-L1RFG676Q
XQ7K325T-L2RF900E	XQ7VX485T-2RF1761I	XQ7Z045-L2RF676I
XQ7K325T-L2RF900I	XQ7VX485T-2RF1930I	XQ7Z045-L2RF900I
XQ7K410T-1RF676I	XQ7VX485T-L2RF1761E	XQ7Z100-1RF1156I
XQ7K410T-1RF676M	XQ7VX485T-L2RF1930E	XQ7Z100-1RF900I
XQ7K410T-1RF900I	XQ7VX690T-1RF1157I	XQ7Z100-2RF1156I
XQ7K410T-1RF900M	XQ7VX690T-1RF1158I	XQ7Z100-2RF900I
XQ7K410T-2RF676I	XQ7VX690T-1RF1761I	XQ7Z100-L2RF1156I
XQ7K410T-2RF900I	XQ7VX690T-1RF1930I	XQ7Z100-L2RF900I
XQ7K410T-L2RF676E	XQ7VX690T-2RF1157I	
XQ7K410T-L2RF676I	XQ7VX690T-2RF1158I	
XQ7VX330T-L2RF1157E	XQ7Z045-1RF900Q	
XQ7VX330T-L2RF1761E	XQ7Z045-1RFG676Q	

Key Dates and Ordering Information

Xilinx will begin cut-over to SPIL bump factory on date code 1625.

Qualification Data

Qualification was completed successfully. Data can be provided upon request.

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
06/27/2016	1.0	Initial release.

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